

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT4500779

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT	
NATURE OF CONVEYANCE:	Corrective Assignment to correct the NAME OF THE RECEIVING PARTY DATA TO TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. previously recorded on Reel 039151 Frame 0211. Assignor(s) hereby confirms the ASSIGNEE'S NAME SHOULD BE TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD..	
RESUBMIT DOCUMENT ID:	504415632	
CONVEYING PARTY DATA		
	Name	Execution Date
	AN-REN ZI	02/16/2016
	CHING-YU CHANG	02/16/2016
RECEIVING PARTY DATA		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.	
Street Address:	NO. 8, LI-HSIN RD. 6	
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK	
City:	HSIN-CHU	
State/Country:	TAIWAN	
Postal Code:	300-77	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	15019836
CORRESPONDENCE DATA		
Fax Number:	(214)200-0853	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	2146515000	
Email:	ipdocketing@haynesboone.com	
Correspondent Name:	HAYNES AND BOONE, LLP IP SECTION	
Address Line 1:	2323 VICTORY AVENUE	
Address Line 2:	SUITE 700	
Address Line 4:	DALLAS, TEXAS 75219	
ATTORNEY DOCKET NUMBER:	2015-1244/24061.3317US01	
NAME OF SUBMITTER:	BRIAN D. GRAHAM	
SIGNATURE:	/Brian D. Graham/	
DATE SIGNED:	07/12/2017	

Total Attachments: 3

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PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3960900

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
AN-REN ZI	02/16/2016
CHING-YU CHANG	02/16/2016
RECEIVING PARTY DATA	
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15019836
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	214-651-5000
Email:	sidney.buchanan@haynesboone.com
Correspondent Name:	HAYNES AND BOONE, LLP.
Address Line 1:	2323 VICTORY AVENUE
Address Line 2:	SUITE 700
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	24061.3317US01
NAME OF SUBMITTER:	DAVID M. O'DELL
SIGNATURE:	/David O'Dell/
DATE SIGNED:	07/13/2016
Total Attachments: 2	
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Docket No.: P20151244US00 / 24061.3317US01
Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|----------------|----|-----------------------------------|
| (1) | An-Ren Zi | of | Hsinchu City 300, Taiwan (R.O.C.) |
| (2) | Ching-Yu Chang | of | Hsin-Chu, Taiwan 300-77 (R.O.C.) |

have invented certain improvements in

PHOTORESIST WITH POLAR-ACID-LABILE-GROUP

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on 02-09-2016 and assigned application number 15/019,836, and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Docket No.: P20151244US00 / 24061.3317US01
Customer No.: 000042717

Inventor Name: An-Ren Zi

Residence Address: 8F., No.15, Ln. 28, Sec. 1, Tiedao Rd., East District
Hsinchu City 300, Taiwan (R.O.C.)

Dated: 2016/2/16

An-Ren Zi
Inventor Signature

Inventor Name: Ching-Yu Chang

Residence Address: No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park
Hsin-Chu, Taiwan 300-77, Republic of China

Dated: 2016/2/16

Ching-Yu Chang
Inventor Signature